



20-3032 A&B

LOW DENSITY EPOXY SYNTACTIC FOAM

DESCRIPTION:

20-3032 is a light weight epoxy for potting, casting, and encapsulating electronic components and assemblies. It is formulated in a convenient 2:1 by volume mix ratio.

20-3032 can also be used for molding and fabricating light weight parts.

FEATURES:

- Chemical, solvent and moisture resistance
- Excellent electrical insulation properties
- Outstanding thermal shock and impact resistance
- Excellent adhesion
- Easy to use low viscosity system

TYPICAL SPECIFICATIONS:

Mix Viscosity @ 25°C cps	6,000
Specific Gravity, 25°C	.75
Hardness, Shore D	70
Pot life, 100 gram mass at 25°C, minutes	60
Standard color	Grey
Dielectric constant, 60 Hz	3.70
Dielectric strength, V/mil	390
Volume resistivity, ohm-cm	10 ¹²
Thermal conductivity, W/m- °K	0.2

INSTRUCTIONS FOR USE:

1. By volume, mix one part Part B catalyst to two parts Part A resin.
2. Cure overnight at room temperature or with mild heat up to 150°F.
3. Since 20-3032 contains low density fillers that will separate during storage, remix part A and part B prior to each use.

IMPORTANT:

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